

	
Class	Subclass
ISSUE CLASSIFICATION	

PATENT NUMBER

U.S. UTILITY Patent Application

Q.I.P.E. <i>KW</i> SCANNED <i>M</i> Q.A. <i>A.G.</i>	PATENT DATE _____
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APPLICATION NO. 09/715000	CONT/PRIOR F	CLASS 257 438	SUBCLASS 780	ART UNIT 2811 2825	EXAMINER Loo
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APPLICANTS

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Hiroaki Tomimori

TITLE

Improved semiconductor wafer surface and method of treating a semiconductor wafer surface

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PTO-2040
12/89

438/687

4381

ISSUING CLASSIFICATION

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)		NOTICE OF ALLOWANCE MAILED	
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ISSUE FEE				
	_____ (Primary Examiner) (Date)		Amount Due	Date Paid
<input type="checkbox"/> The terminal ____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) (Date)		ISSUE BATCH NUMBER	

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